Gallium Nitride 50V, 35W, 2.45GHz RF Power Transistor

Description

The STAV25035C6 is a 35watt, CW capable, GaN HEMT, ideal for general applications from 2.4 to 2.5GHz It features high gain, high efficiency and low cost, in 10*6mm plastic open cavity package, enabling surface mounted on PCB through grounding vias directly.

There is no guarantee of performance when this part is used outside of stated frequencies.

 Typical Class AB RF CW performance with device soldered through grounding vias Vds=50V, Vgs=-2V

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
2400	44.65	29.2	65.7	20.41	45.95	39.4	74.5
2450	44.29	26.9	64.8	19.72	45.82	38.2	74.6
2500	44.17	26.1	65.8	19.28	45.65	36.7	75.2

Applications

- 2.45GHz RF Energy
- S band amplifier

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set VGS to the pinch--off (VP) voltage, typically -5 V

- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

- Turning the device OFF 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+200	Vdc
GateSource Voltage	V _{GS}	-8 to +0.5	Vdc
Operating Voltage	V _{DD}	55	Vdc
Maximum gate current	lgs	4.8	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _c	+150	°C
Operating Junction Temperature	TJ	+225	°C
Table 2. Thermal Characteristics			•

CharacteristicSymbolValueUnitThermal Resistance, Junction to Case by FEA
T_c= 85°C, at Pout=35W CW, mounted on high density viasReJC4°C /W

Table 3. Electrical Characteristics (TA = 25° unless otherwise noted)

DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
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Drain-Source Breakdown Voltage	VGS=-8V; IDS=4.8mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 4.8mA	V _{GS(th)}	-4	-3	-2	V
Gate Quiescent Voltage	VDS =50V, IDS=48mA, Measured in Functional Test	V _{GS(Q)}		-3		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	2.45GHz, Pout=35W pulse CW					
	All phase,	VSWR		10:1		
	No device damages					

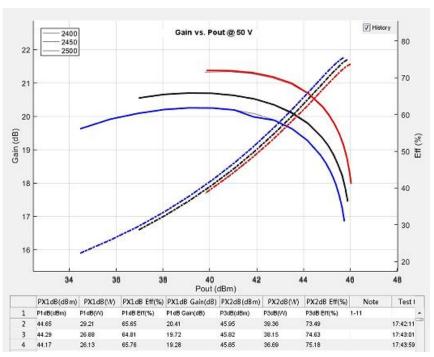
Figure 1:Pin Definition(Top View)

	36	35	34	33	32	31	30	29	28	27	26	25	
1													24
2													23
3													22
4													21
5													20
6													19
	7	8	9	10	11	12	13	14	15	16	17	18	

Pin No.	Symbol	Description
1-7,12,13,18-25,30,31,36	GND	DC/RF Ground
8,9,10,11,14,15,16,17	Vgs/RF In	Vgs and RF input
26,27,28,29,32,33,34,35	Vds/RF out	Vds and RF output
Package Base	GND	DC/RF Ground.

Typical characters

Figure 2: Efficiency and power gain as function of Pout



CW

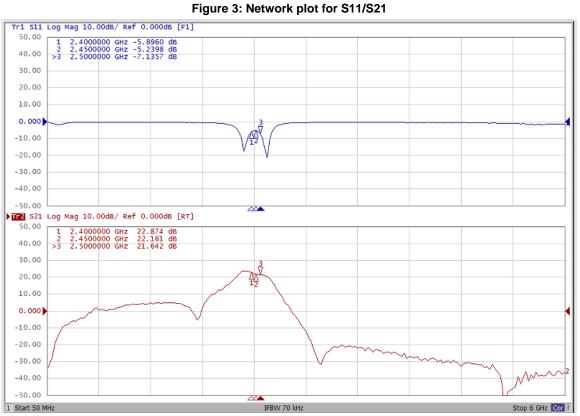


Figure 4: Picture of application board of 3.4-3.8GHz

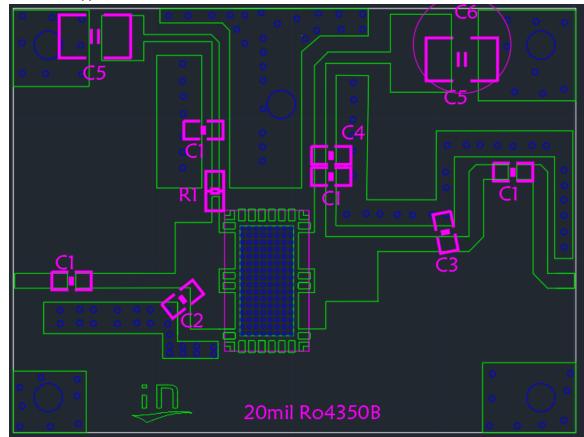
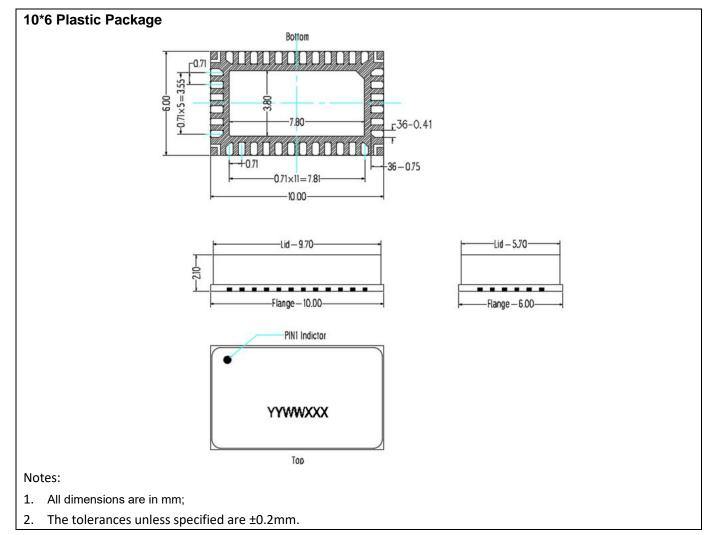


Table 4. Bill of materials of application board (RO4350B 20mils,PCB layout upon request)

	BOM					
Component	Value	Quantity				
C1	12pF	4				
C5	10uF	2				
R1	10 ohm	1				
C4	1uF	1				
C3	1.2pF	1				
C2	3pF	1				
C6	470uF	1				

Package Dimensions



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2024/9/28	V1.0	Preliminary Datasheet Creation

Application data based on: ZXY-24-34

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